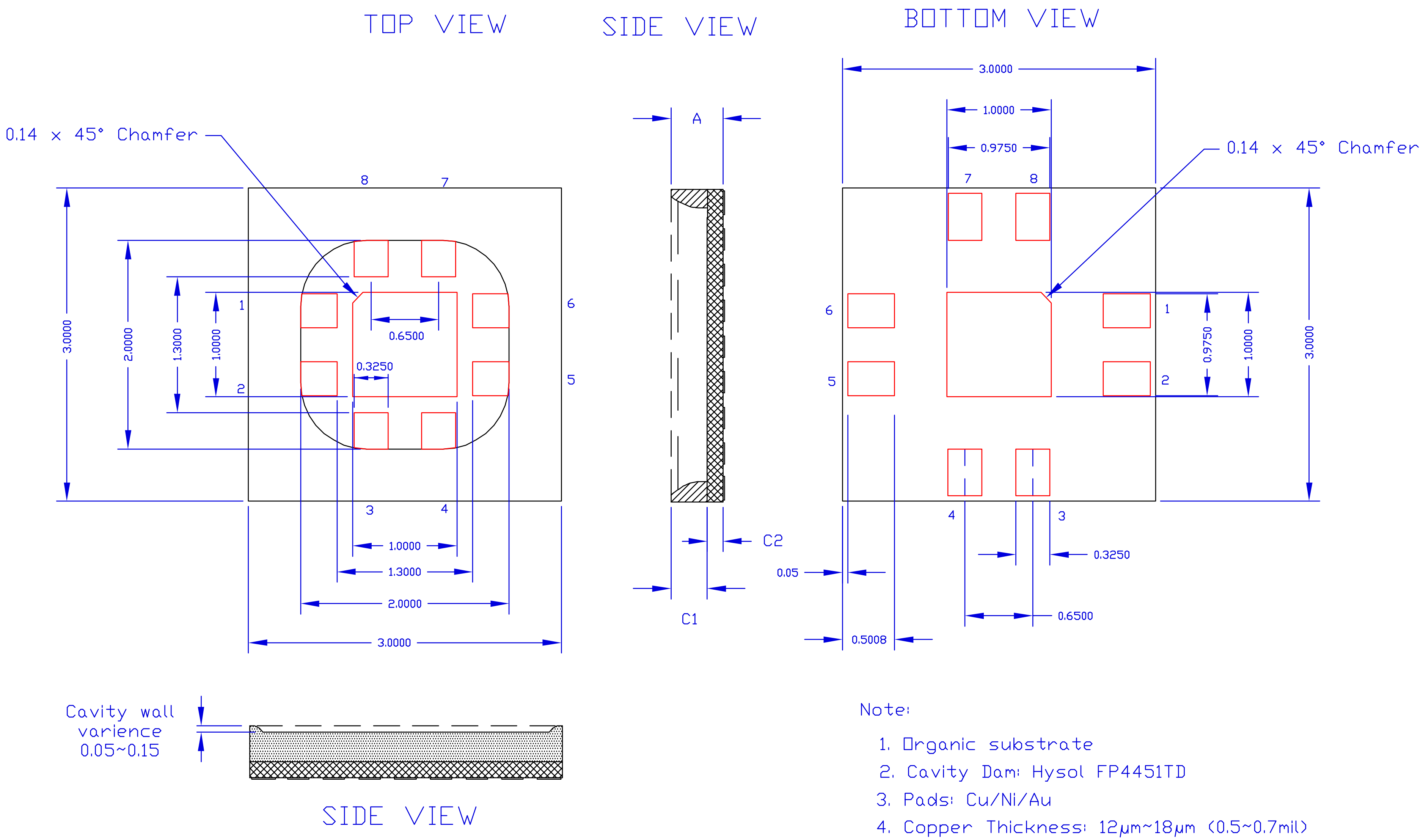
REV	DESCRIPTION	DATE	APPROVAL



Note:

1. Organic substrate
2. Cavity Dam: Hysol FP4451TD
3. Pads: Cu/Ni/Au
4. Copper Thickness: 12μm~18μm (0.5~0.7mil)
5. Bonding Pad Gold Thickness: 1.3μm (50 micro-inch)
6. PCB Pads Gold Thickness: 0.13μm (5 micro-inch)
7. Nickel Thickness: 3.8μm (150 micro-inch)
8. All Dimensions Are mm

HEIGHT TABLE

SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL +/-	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

TOLERANCES UNLESS NOTED:	
X.XX	±
X.XXX	±
X.XXXX	±
ANGLES	±

ALL DIMENSIONS ARE IN:
☐ INCHES ☐ MILLIMETERS

THIRD ANGLE
PROJECTION:

APPROVALS		DATE
DRAWN	TA	11/29/08
ENG		
MFG		
QA		
CUST		
REVISED		

Mirror
Semiconductor ™

TITLE 8-LEAD 3MM P=0.65MM
A-QFN (AIR) OPEN CAVITY

SCALE	SIZE	DRAWING NO.	REV
NONE	A	460810	A

DO NOT SCALE DRAWING
SHEET 1 OF 1